



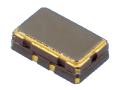
**Specification** AXLE5032S Rev.: 2 Date: 2025-01-21

Oscillator type: Low Phase Noise TCXO in 5x3.2 mm ceramic package for

**Space Application (Space COTS version)** 

## **Features:**

- Lower cost Commercial Off-The-Shelf version (COTS)
- Dedicated for LEO~MEO applications
- Manufactured according to MIL-PRF-55310 Level "S"
- Radiation hardened 40 krad(Si) total dose (TID)
- Radiation hardened SEL immune > 90 MeV
- ITAR Free Manufactured in Europe
- **Low Phase Noise**
- High Frequency Stability
- Hermetical sealed 5x3.2 mm ceramic package
- Short lead time



## Models:

Item	Engineering Model	Flight Model	Note
	(EM)	(FM)	
Quartz Synthetic HiQ Quartz,		Synthetic HiQ Quartz,	1
Crystal	AT-cut	AT-cut	
Electrical COTS parts		COTS parts	-
Components		Automotive Grade	
		and/or HighRel Heritage	
Mechanical	Ceramic package with	Ceramic package with	-
Components	metal cover	metal cover	
Workmanship	Hybrid manufacturing	Hybrid manufacturing	-
Rad Hard	-	40 krad(Si) TID	2
	Acceptance Testi	ng	
Screening Test procedure as		X	3
Group-B	commercial models	X	-
Group-C	=	On request	4

## Notes:

- 1. Swept Quartz material available on request.
- Tested up to 50 krad and SEE tested up to 125 MeV·cm²/mg
  Screening procedure can be modified IAW customer requirements.
- 4. Group-C (LAT) can be performed based on customer requirements.

# **Ordering Code:**

Model	Product category	Options	Revision	Frequency [MHz]
AXLE5032S	EM	See table 1	Rev.2	10.000 ~ 50.000
	FM			

Example: AXLE5032S-FM-V-C\_Rev.2 - 40.000 MHz





### 0. Contents:

- 1. Electrical specification
- 2. Mechanical specification & Handling
- 3. Applicable documents
- 4. General flow of manufacturing
- 5. Acceptance Testing
  - 5.1 Screening
  - 5.2 Group B inspection
  - 5.3 Electrical measurements
- 6. Radiation
- 7. Components, Materials and Processes
- 8. Marking
- 9. Data Documentation
- 10. Handling, Packaging and Delivery
- 11. Specification History





## 1. Electrical specification

Parameter	min.	typ.	max.	Unit	Condition
Frequency range	10		50	MHz	
Standard frequencies (Note 3)	20.000	/ 40.000 /	50.000	MHz	
Frequency stability				•	·
Initial tolerance @ +25°C		±0.3	±1	ppm	V <sub>C</sub> = 1.5 V
vs. operating temperature range		±0.3	±1	ppm	
vs. supply voltage variation (pushing)			±0.2	ppm	Vs ±5%
vs. load change (pulling)			±0.2	ppm	R∟ ±5%
Long term (aging) 1 <sup>st</sup> year			±1	ppm	@ +40°C
Long term (aging) 5 years			±3	ppm	@ +40°C
vs. radiation			±1.5	ppm	(Note 4)
Frequency adjustment range					•
Electronic Frequency Control (EFC)	±5	±10		ppm	Option 1 = "V" (Note 5, 6)
EFC voltage V <sub>C</sub>	0.5	1.5	2.5	٧	
EFC slope ( $\Delta f / \Delta V_c$ )		Positive			
EFC input impedance	100			kΩ	
RF output – Option 2 = "C" (CSW)		•		•	·
Signal waveform	Clip	ped sine w	/ave		
Load R∟	10	) kΩ // 10	pF		±5%
Output voltage	0.8	1.2		Vpp	
Phase noise	Please consult factory		actory		
	9	ee table 1	A		
RF output – Option 2 = "H" (HCMOS)					
Signal waveform		LVCMOS			
Load R <sub>L</sub>		10 pF			±10%
Symmetry (duty cycle)	45		55	%	@ V <sub>S</sub> /2
Rise & fall time			5	ns	@ 10% ~ 90% Vs
Phase noise	Pleas	e consult fa	actory		
	9	see table 1	В		
Supply voltage Vs	3.15	3.3	3.45	V	
Current consumption			6	mA	Option 2 = "C"
			8	mA	Option 2 = "H"
Operating temperature range	-40		+85	°C	

Table 1 – Electrical Performance and Characteristics

### Notes:

- 1. Terminology and test conditions are according to IEC60679-1 and MIL-PRF-55310 unless otherwise stated
- 2. Classification (MIL-PRF-55310): Type 5 (TCXO), Class 2 (Hybrid Technology), Product Level "S"
- 3. Arbitrary frequency within specified frequency range on request
- 4. Radiation of 40 krad(Si) total dose (TID). Radiation low dose test of TCXO series was performed up to 50 krad. Please consult factory for radiation report.
- 5. For option 1 = "N" (No EFC) pin 1 can be left open.
- 6. Tuning range is sufficient to compensate for initial tolerance, temperature stability, pushing, pulling, min. of 5 years aging & radiation of 40 krad(Si)





## **Ordering Code**

Model	Product category	Option 1 [EFC]	Option 2 [Output]	Revision	Frequency [MHz]
AXLE5032S	EM	"N" = No EFC	"C" = Clipped Sine Wave (CSW)	Rev.2	10.000 ~ 50.000
	FM	"V" = EFC	"H" = HCMOS (LVCMOS)		

### **Examples:**

- (1) AXLE5032S-FM-V-C\_Rev.2 40.000 MHz (with EFC and CSW output)
- (2) AXLE5032S-FM-N-H\_Rev.2 40.000 MHz (without EFC and HCMOS output)

## Typical phase noise performance

Offeet	Frequ	Frequency		
Offset	20 MHz	50 MHz	Unit	
1 Hz	-65	-60	dBc/Hz	
10 Hz	-95	-90	dBc/Hz	
100 Hz	-124	-115	dBc/Hz	
1 kHz	-146	-135	dBc/Hz	
≥10 kHz	-156	-154	dBc/Hz	

Table 1A – Clipped Sine Wave Output (CSW)

Offers	Frequ	Frequency		
Offset	20 MHz	50 MHz	Unit	
1 Hz	-63	-56	dBc/Hz	
10 Hz	-94	-86	dBc/Hz	
100 Hz	-123	-111	dBc/Hz	
1 kHz	-144	-131	dBc/Hz	
≥10 kHz	-154	-152	dBc/Hz	

Table 1B – HCMOS Output (LVCMOS)

Note: For better phase noise performance please see our AXLE7050S series.

## **Absolute Maximum Ratings**

Parameter	Min.	Max.	Unit	Condition / Remark
Supply Voltage V <sub>S</sub>	-0.5	4.5	V	V <sub>S</sub> to GND
Control Voltage V <sub>C</sub>	-0.5	4.5	V	V <sub>s</sub> to GND
Load R <sub>L</sub> – CSW Output	500	∞	Ω	Must not cause any damage
Load R <sub>L</sub> – HCMOS Output	0	15	pF	
Operable temperature range	-50	+95	°C	Operation of unit without any damage
Storage temperature range	-55	+105	°C	-

Table 2 - Maximum Ratings



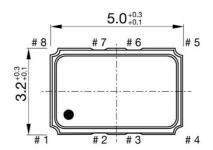


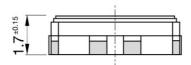
## 2. Mechanical specification & Handling

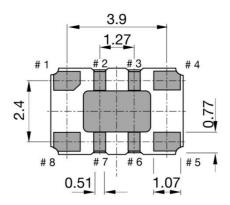
Parameter	Min.	Тур.	Max.	Unit	Condition
Enclosure (see drawing) (LxWxH)	5.	0 x 3.2 x 1	.7	mm	Hermetically sealed
Weight			1	g	
Case	Ceran	nic packago	e with	-	
	metal cover				
Pins	NiAu plated		-		
Crystal Package (top side)	SAC3 soldered		-		
Moisture Sensitivity Level	MSL 1		-	IPC/JEDEC J-STD-020C	
Cleaning	Washable		-		
Electrostatic Discharge (ESD)	MM Class M2: < 200 V		-		
Reflow Profile	max. +26	60°C for 10	seconds	-	IPC/JEDEC J-STD-020C

Table 3 - Mechanical specification & Handling

# **Enclosure drawing**







## **Pin connections**

Pin #	Symbol	Function
1	Vc	Control Voltage (EFC) *
2	D.N.C.	Do Not Connect
3	D.N.C.	Do Not Connect
4	GND	Ground
5	RF OUT	RF Output
6	D.N.C.	Do Not Connect
7	D.N.C.	Do Not Connect
8	Vs	Supply Voltage

<sup>\*</sup> For option 1 = "N" (no EFC) pin 1 can be left open

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## 3. Applicable documents

The following specifications and standards are part of this specification:

ESCC21300 Terms, Definitions, Abbreviations, Symbols and Units

MIL-STD-55310 General specification for crystal-controlled oscillators

MIL-STD-202 Test Method Standard for electronic and electrical component parts

MIL-STD-883 Test Method Standard for Microcircuits

IEC 60679-1 Quartz crystal-controlled oscillators of assessed quality

Part 1: Generic specification

## Order of precedence

In the event of a conflict between the text of this specification and the references cited herein, the order of precedence shall be as follows:

- (1) Purchase order
- (2) Oscillator detail specification AXLE5032S
- (3) Generic specification MIL-PRF-55310
- (4) Other documents

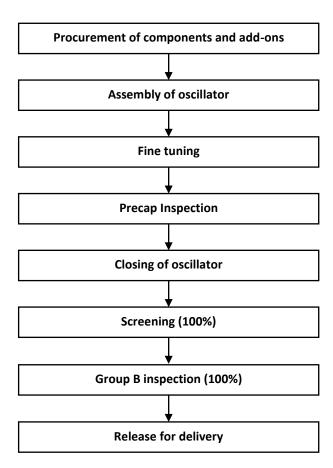
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## 4. General flow of manufacturing

The figure below shows the overall flow for manufacturing:







# 5. Acceptance Testing

### 5.1 Screening

Table 4 shows the screening procedure according to MIL-PRF-55310 Product level "S".

#	Test	Reference
1	Electrical measurements at room temperature (Initial)	IEC 60679-1 (see Table 1)
2	Thermal Shock	MIL-STD-202, Method 107, Condition A-1
3	Burn-in (load) *1	MIL-PRF-55310
4	Seal Test – Fine Leak *2	MIL-STD-202, Method 112, Condition D
5	Electrical measurements vs. temperature	IEC 60679-1 (see Table 1)
6	Electrical measurements at room temperature (Final)	IEC 60679-1 (see Table 1)
7	External Visual Inspection	ESCC20500 / MIL-STD-883 Method 2009

Table 4 – Screening procedure

#### Notes:

- 1. Burn-in can be performed at any step after assembly and is usually performed as pre-aging procedure
- 2. Fine leak test is performed for the crystal, which is a 100% test during crystal manufacturing

Table 5 shows the detailed test conditions for each step in table 4.

#	Test	Test Condition	
1	Electrical measurements at	@ T <sub>amb</sub> = 25°C±3°C (unless otherwise stated)	
1	room temperature (Initial)	Table 8	
2	Thermal Shock	-40 to +80°C, 25 cycles, max. 5 minutes transfer time,	
	THEITHAI SHOCK	15 minutes dwell time	
3	Burn-in (load)	@ T = $+85$ °C for 10 days (nominal V <sub>S</sub> and Load)	
4	Seal Test – Fine Leak	MIL-STD-202, Method 112, Condition D	
5	Electrical measurements vs.	@ T = $T_{MIN}$ to $T_{MAX}$ , 5°C steps with ±1°C tolerance	
5	temperature	Limits: See Table 1	
6	Electrical measurements at	@ T <sub>amb</sub> = 25°C±3°C (unless otherwise stated)	
0	room temperature (Final)	Table 8	
7	External Visual Inspection	ESCC20500 / MIL-STD-883 Method 2009	

Table 5 – Detailed test conditions for screening procedure

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## 5.2 Group B inspection (Aging)

Table 6 shows the Group B inspection procedure.

#	Test	Reference
1	Aging test	MIL-PRF-55310, Clause 4.7.1.5 Product level "S"
2	Electrical measurements at room temperature (Final)	IEC 60679-1 (see Table 1)

Table 6 - Group B inspection procedure

#### Notes:

1. Group B inspection may be performed before or after screening procedure. Final electrical measurements are only performed once after completion of screening and Group B inspection.

Table 7 shows the detailed test conditions for each step in table 6.

#	Test	Test Condition
1		@ T <sub>amb</sub> = 30°C±3°C for 10 days (nominal V <sub>S</sub> and Load)
	Aging test	Frequency measurement every hour
		Limits Aging: See Table 1
2	Electrical measurements at	@ T <sub>amb</sub> = 25°C±3°C (unless otherwise stated)
	room temperature (Final)	Table 8

Table 7 – Detailed test conditions for Group B inspection procedure

### 5.3 Electrical measurements

Table 8 shows all electrical measurements with its respective conditions and limits, which are performed for all models. If not otherwise stated all measurements are performed at  $T_{amb} = 25^{\circ}C \pm 3^{\circ}C$  and after a sufficient stabilization time.

#	Parameter	Test Method	Conditions	Initial	Final	Limits
1	Initial frequency	IEC 60679-1	$V_S = 3.3 \text{ V, } R_L = 10 \text{ k}\Omega \text{ // } 10 \text{ pF}$	Χ	Χ	Table 1
2	Output level	IEC 60679-1	$V_S = 3.3 \text{ V, } R_L = 10 \text{ k}\Omega \text{ // } 10 \text{ pF}$	Χ	Χ	Table 1
3	Current consumption	IEC 60679-1	$V_S = 3.3 \text{ V, } R_L = 10 \text{ k}\Omega \text{ // } 10 \text{ pF}$	Χ	Χ	Table 1
4	Tuning range	IEC 60679-1	$V_S = 3.3 \text{ V, } R_L = 10 \text{ k}\Omega \text{ // } 10 \text{ pF}$	-	Χ	Table 1
5	Phase noise	IEC 60679-1	$V_S = 3.3 \text{ V, } R_L = 10 \text{ k}\Omega \text{ // } 10 \text{ pF}$	-	Χ	Table 1

Table 8 – Electrical measurements





### 6. Radiation

The oscillator is capable of meeting all electrical performance requirements after exposure to a total ionizing dose (TID) of 40 krad(Si). The oscillator is based on a Space COTS approach and the radiation performance has been verified by a radiation test (Co 60) up to 50 krad(Si) and a SEE test up to 125 MeV·cm²/mg with the very similar TCXO series AXLE7050S. The oscillator is SEL immune and didn't show any other destructive events during the radiation tests. Radiation reports are available on request.

### 7. Components, Materials and Processes

The oscillators are built on the basis of the following requirements for components, materials and processes:

- All add-on components are specially-selected commercial off-the-shelf (COTS) versions.
- The crystal is made of synthetic high Q quartz material with low inclusion density and low etch channel density (according to IEC 60758).
- The oscillator and crystal unit are in hermetically sealed packages.
- The manufacturing is done in hybrid technology.
- No pure tin is used inside the oscillator, as package or lead finish. The crystal resonator on top of the main package is SAC3 soldered. A version with SnPb solder for full tin whisker mitigation is available on request.
- The marking is resistant to Zestron VD, Isopropyl alcohol (99% pure) and Ethyl alcohol (99.5% pure), tested in accordance with ESCC24800.

### 8. Marking

The marking of the parts is accordance with ESCC21700. The content is as follows:

(1) First line: Frequency & Lot number

(2) Second line: Serial number







### 9. Data Documentation

#### General

With each delivery the following data documentation package is supplied:

- (1) Certificate of Conformity (CoC)
- (2) Test data (full report of all inspections)

The following additional documents can be delivered on request:

- Declared Component List
- Equipment List (Testing & Measuring)
- Radiation Report

### **Certificate of Conformity**

The certificate includes the following content:

- Full company information (Logo, Name, Address)
- Type and specification (part number and revision)
- Nominal frequency
- Number of purchase order
- Lot identification
- Range of serial numbers
- Number of delivered parts
- Authorized signature in behalf of manufacturer (including stamp and date)

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## 10. Handling, Packaging and Delivery

- Some add-ons are susceptible to damage by electrostatic discharge. Therefore, suitable ESD precautions for handling during use and manufacturing must be employed.
- In order to minimize the risk of damage, all kinds of shock during handling and manufacturing must be avoided.
- The parts are packaged in a way to ensure adequately safeguarding against mechanical and electrical injury and deterioration due to humidity.
- The primary package is labeled as ESD sensitive component.

## 11. Specification History

Rev.	Drawing	Date	Remarks	Author	Checked
		[dd.mm.yyyy]			
1	D0	14.04.2023	First issue	НН	НН
2	D0	20.01.2025	Order options updated. Parameters updated and additional information added	НН	НН
2	D1	21.01.2025	Solder information & package picture updated	НН	НН

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